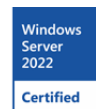


G363-SR0-LAX1

HPC/AI Server - 5th/4th Gen Intel® Xeon® Scalable -
3U DP HGX™ H100 4-GPU DLC



Key Features

- Liquid-cooled NVIDIA HGX™ H100 4-GPU
- CPU+GPU direct liquid cooling solution
- 900GB/s 4th-generation NVIDIA NVLink™
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 16 x DIMMs
- Dual ROM Architecture
- 2 x 10Gb/s LAN ports via Broadcom® BCM57416
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 8 x 2.5" Gen5 NVMe/SATA/SAS hot-swap bays
- 1 x M.2 slot with PCIe Gen4 x4 interface
- 6 x LP PCIe Gen5 x16 slots
- 2+1 3000W 80 PLUS Titanium redundant power supplies

Specification

Dimensions	3U (W448 x H131 x D850.2 mm)	Modular GPU	Liquid-cooled NVIDIA HGX™ H100 with 4 x SXM5 GPUs
Motherboard	MS63-HD2	PCIe Expansion Slots	6 x LP PCIe Gen5 x16 *The ambient temperature is limited to 30°C when NVIDIA® BlueField®-3 DPUs/SuperNIC™ are installed.
CPU	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 385W	I/O Ports	Front: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN (default) Rear: 2 x RJ45, 1 x MLAN
OS Compatibility	OS Support List	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS 12Gb/s
Socket	2 x LGA 4677 (Socket E)	TPM	1 x TPM header (SPI), Optional TPM2.0 kit: CTM010
Chipset	Intel® C741	Power Supply	2+1 3000W 80 PLUS Titanium redundant power supplies AC Input: 115-240V *The system power supply requires C19 power cord.
Memory	8-Channel DDR5 RDIMM, 16 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s [4th Gen Intel Xeon] Up to 4800 MT/s [Intel Xeon Max Series] Up to 4800 MT/s	System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
LAN	Front: 2 x 1Gb/s LAN (1 x Intel® I350-AM2), Support NCSI 1 x 10/100/1000 Mbps Management LAN Rear: 2 x 10Gb/s LAN (1 x Broadcom® BCM57416), Support NCSI 1 x 10/100/1000 Mbps Management LAN	System Fans	4 x 80x80x80mm
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP	Operating Properties	Operating: 10°C to 40°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing) *To ensure system stability and prevent condensation, when the relative humidity exceeds 50%, the coolant inlet temperature must be higher than the dry-bulb temperature and it should not exceed 45°C.
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe/SATA/SAS [1] Internal M.2: 1 x M.2 (2280/22110), PCIe Gen4 x4 [1] SAS card is required to support SAS drives.	Packaging Content	1 x G363-SR0-LAX1 1 x Mini-DP to D-Sub cable 6 x Carriers 1 x L-shape Rail kit
RAID	Intel® SATA RAID 0/1/10/5 Support optional RAID add-in cards	Ordering Part Numbers	6NG363SR0DR000LBX1*



Learn more at: <https://www.gigabyte.com/Enterprise>

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